
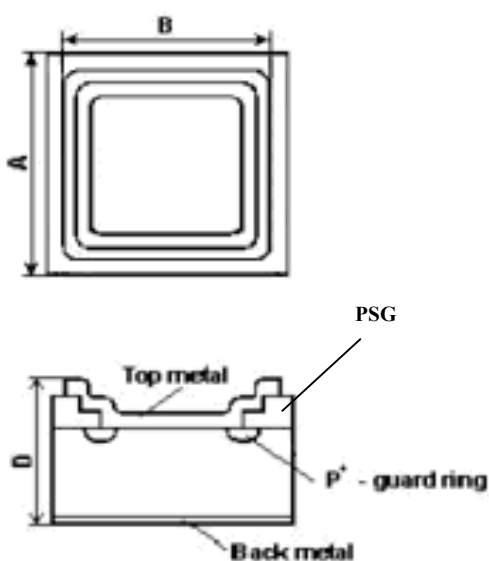


SCHOTTKY DIODES KDS-00520. PRELIMINARY



Aug. 2011

 VSP-MIKRON	0,5A/20V. Die Size-18mil.			
Electrical Characteristics	Symbol	Unit	Spec. limit	Die Sort
Breakdown Voltage @ $I_R=10\text{mA}$	V_B	V	20	25
Average Rectified Forward Current	$I_{F(AV)}$	A	0,5	-
DC Forward Voltage @ 25°C , $I_F=0,5\text{A}$	V_F	V	0,47	0,45
Maximum Reverse Current @ 25°C , $V_R=23\text{V}$ 25°C , $V_R=20\text{V}$ 100°C , $V_R=20\text{V}$	I_R	MA	- 0,150 10,0	0,150 0,100 9,0
Peak Forward Surge Current 8,3ms single half sine-wave superimposed on rated load (JEDEC METHOD)	I_{FSM}	A	5,0	-
Peak Repetitive Reverse Surge Current @ $2,0\mu\text{s}$, $f=1\text{kHz}$., $T_J<150^\circ\text{C}$.	I_{RRM}	A	0,5	
Electrostatic Discharge Voltage. JEDEC Method. ESD HBM. Contact.	ESD	kV	± 8 (contact)	
Voltage Rate of Change	dV/dt	V/ μS	10.000	
Operating Junction Temperature	T_J	$^\circ\text{C}$	150	



DIM	ITEM	μm
A_x A_y	Die Size	460 460
B_x B_y	Top Metal Size	340 340
D	Thickness	200max.
Scribe line Width		80

Top metal: a) **Al** – for Wire Bonding;
 b) **Al-Ni-Ag** – for Soldering.
 Backside metal: **Ti-Ni-Ag**.